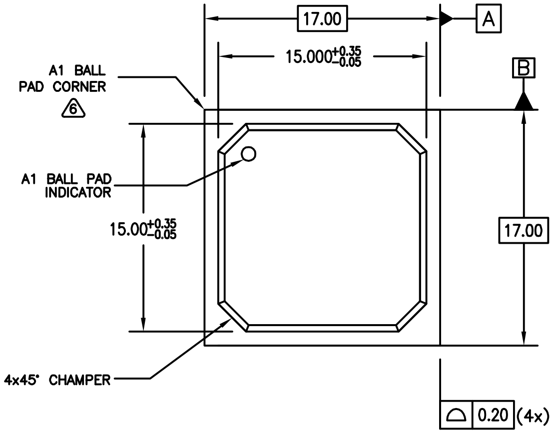
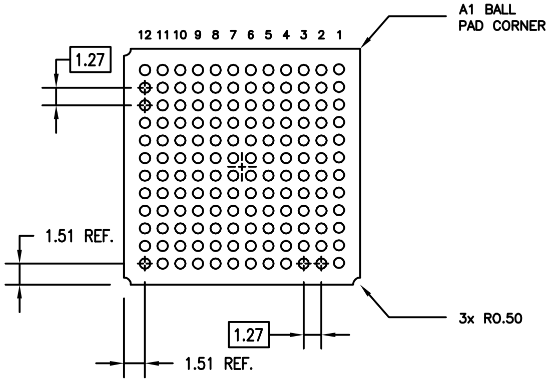
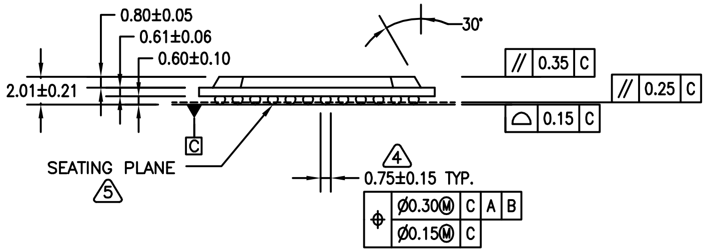


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.27 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C
5. PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO LEADED (-), LEAD FREE (+) PKG. CODES.
8. PACKAGE CODE: V144T-1

-DRAWING NOT TO SCALE-

MAXIM

TITLE:
PACKAGE OUTLINE, 144 BALLS PBGA, THERMALLY ENHANCED
17.0x17.0x2.01mm, 1.27mm PITCH, 4 LAYER

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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